


<div><div></div><div>Telink</div></div>				<div>Telink Semiconductor (Shanghai) CO., LTD Phone: +8621 2028 1118 Fax: 8621 5038 8081 1500 Zuchongzhi Road Bldg 3 PuDong District, Shanghai, China 201203</div>					
Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		HuaTian Technology (Nan Jing) Co.,Ltd							
Product Name:		TLSR8253F512AT32							
Weight(Unit):		63.9936 mg						Date:	2023/10/17
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	0.5000	Silicon	7440-21-3	0.5000	100.00%	0.78%	1000000
Lead Frame	A194 CU	AAMI	19.9936					31.24%	
				Copper (Cu)	7440-50-8	19.3938	97.00%	30.31%	970000
				Iron (Fe)	7439-89-6	0.4599	2.30%	0.72%	23000
				Lead (Pb)	7439-92-1	0.0020	0.01%	0.00%	100
				Phosphorus (P)	7723-14-0	0.0200	0.10%	0.03%	1000
				Zn	7440-66-6	0.0160	0.08%	0.02%	800
				Ag	7440-22-4	0.1020	0.51%	0.16%	5100
DAF	ATB-120U	上海盘石	2.5600	Modified Epoxy Resin	Proprietary	1.74848	68.30%	4.58%	683000
				Epoxy resin	Proprietary	0.512	20.00%	0.80%	200000
				Aromatic polyamine	Proprietary	0.2432	9.50%	0.38%	95000
				[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	0.0512	2.00%	0.08%	20000
				4,4'-Isopropylidenediphenol	80-05-7	0.00512	0.20%	0.01%	2000
绝缘胶	L1-403N	理均	3.0000	Diethylene glycol monoethyl ether acetate	112-15-2	0.3	10.00%	4.69%	100000
				Silica	15468-32-3	1.8	60.00%	2.81%	600000
				Acylate resin	15625-89-5	0.45	15.00%	0.70%	150000
				Epoxy resin	Proprietary	0.45	15.00%	0.70%	150000
Wire	R2SP	乐金	2.9400	Ag	7440-22-4	2.7930	95.0000%	4.00%	950000
				Pd	7440-05-3	0.1470	5.0000%	0.23%	50000
Mold Compound	CEL-9240H	RESONAC Materials	32.0000					50%	
				Epoxy Resin 1	Trade secret	0.9600	3.00%	1.50%	30000
				Epoxy Resin 2	Trade secret	0.9600	3.00%	1.50%	30000
				Epoxy Resin 3	Trade secret	0.9600	3.00%	1.50%	30000
				Hardener	Trade secret	1.2800	4.00%	2.00%	40000
				Catalyst	Trade secret	0.1600	0.50%	0.25%	5000
				Carbon black	1333-86-4	0.0640	0.20%	0.10%	2000
				Amorphous silica1	60676-86-0	25.3760	79.30%	39.65%	793000
				Amorphous silica2	7631-86-9	2.2400	7.00%	3.50%	70000
Plating	TIN	AISEN	3.0000	Tin	7440-31-5	2.9997	99.99%	3.73%	999900
				other	Trade secret	0.0003	0.01%	0.00%	100
Total			63.9936			63.9936	100%		1000000